

Main product characteristics

$I_{F(AV)}$	1 A
V_{RRM}	60 V
T_j (max)	150° C
V_F (max)	0.57 V

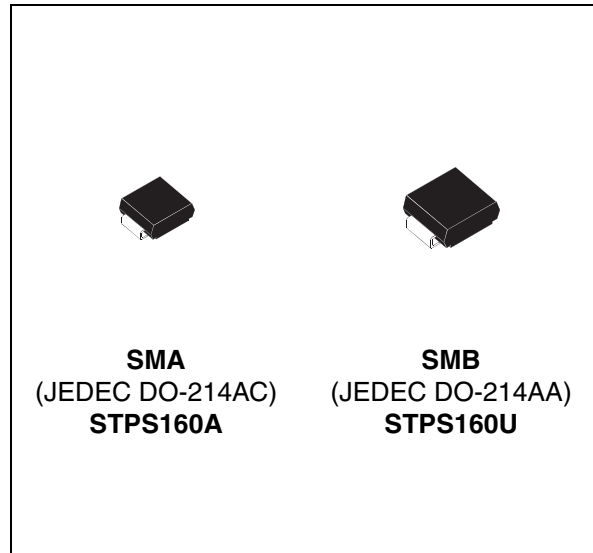
Features and benefits

- Very small conduction losses
- Negligible switching losses
- Low forward voltage drop
- Surface mount miniature packages
- Avalanche capability specified

Description

Single chip Schottky rectifiers suited to switched mode power supplies and high frequency DC to DC converters.

Packaged in SMA and SMB, this device is especially intended for surface mounting and used in low voltage, high frequency inverters, free wheeling and polarity protection applications.

**Order codes**

Part number	Marking
STPS160A	GA6
STPS160U	E16

1 Characteristics

Table 1. Absolute ratings (limiting values)

Symbol	Parameter		Value	Unit
V _{RRM}	Repetitive peak reverse voltage		60	V
I _{F(AV)}	Average forward current	T _L = 130° C δ = 0.5	1	A
I _{F(SM)}	Surge non repetitive forward current	t _p = 10 ms sinusoidal	75	A
I _{RRM}	Repetitive peak reverse current	t _p = 2 μs F = 1 kHz square	1	A
I _{RSM}	Non repetitive peak reverse current	t _p = 100 μs square	1	A
P _{ARM}	Repetitive peak avalanche power	t _p = 1 μs T _j = 25° C	2400	W
T _{stg}	Storage temperature range		-65 to + 150	°C
T _j	Maximum operating junction temperature ⁽¹⁾		150	°C
dV/dt	Critical rate of rise of reverse voltage		10000	V/μs

1. $\frac{dP_{tot}}{dT_j} < \frac{1}{R_{th(j-a)}}$ condition to avoid thermal runaway for a diode on its own heatsink

Table 2. Thermal resistance

Symbol	Parameter		Value	Unit
R _{th(j-l)}	Junction to lead	SMA	30	°C/W
		SMB	23	

Table 3. Static electrical characteristics

Symbol	Parameter	Test conditions		Min.	Typ.	Max.	Unit
I _R ⁽¹⁾	Reverse leakage current	T _j = 25° C	V _R = V _{RRM}			4	μA
		T _j = 125° C			1.1	4	mA
V _F ⁽²⁾	Forward voltage drop	T _j = 25° C	I _F = 1 A			0.67	V
		T _j = 125° C			0.49	0.57	
		T _j = 25° C	I _F = 2 A			0.8	
		T _j = 125° C			0.58	0.65	

1. Pulse test: t_p = 5 ms, δ < 2%

2. Pulse test: t_p = 380 μs, δ < 2%

To evaluate the conduction losses use the following equation:

$$P = 0.49 \times I_{F(AV)} + 0.08 I_{F(RMS)}^2$$

Figure 1. Average forward power dissipation versus average forward current

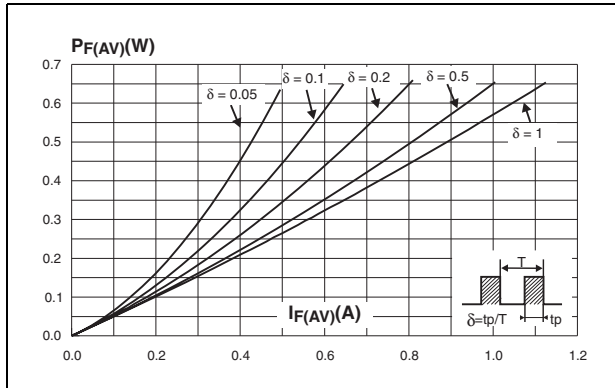


Figure 2. Average forward current versus ambient temperature (delta = 0.5)

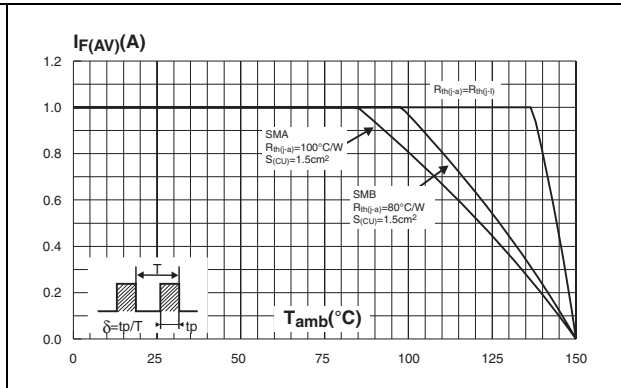


Figure 3. Normalized avalanche power derating versus pulse duration

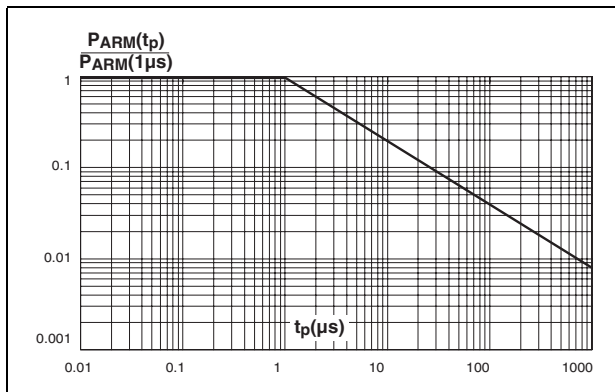


Figure 4. Normalized avalanche power derating versus junction temperature

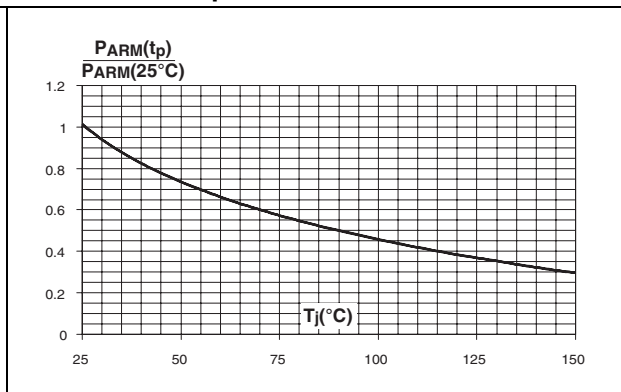


Figure 5. Non repetitive surge peak forward current versus overload duration (maximum values) (SMA)

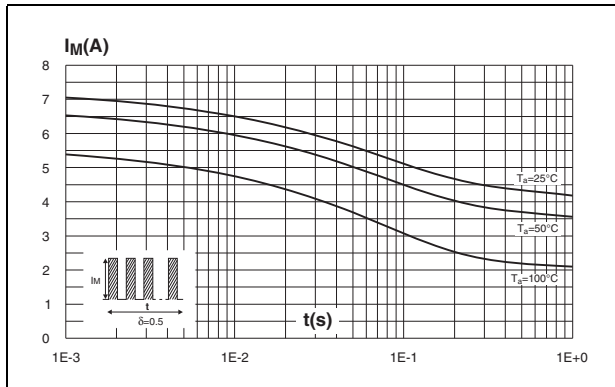


Figure 6. Non repetitive surge peak forward current versus overload duration (maximum values) (SMB)

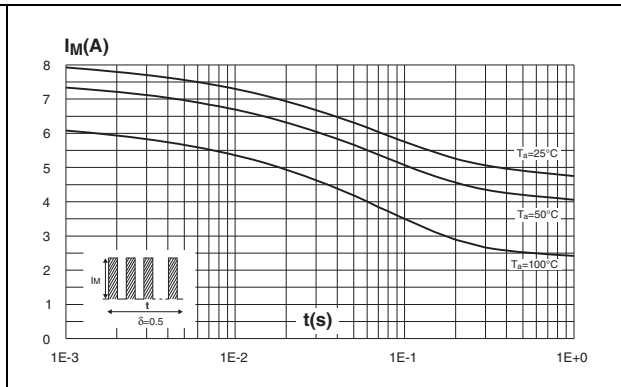


Figure 7. Relative variation of thermal impedance junction to ambient versus pulse duration (epoxy printed circuit board, $e_{(Cu)} = 35 \mu\text{m}$, recommended pad layout) (SMA)

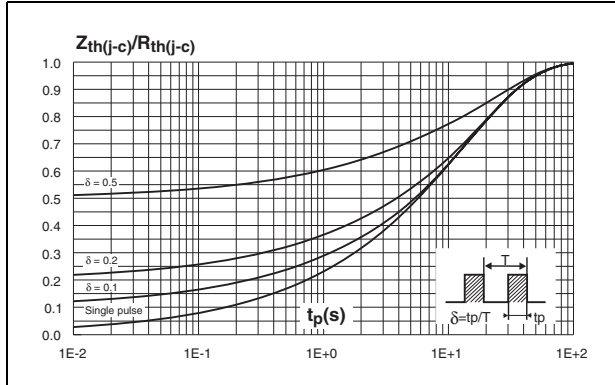


Figure 8. Relative variation of thermal impedance junction to ambient versus pulse duration (epoxy printed circuit board, $e_{(Cu)} = 35 \mu\text{m}$, recommended pad layout) (SMB)

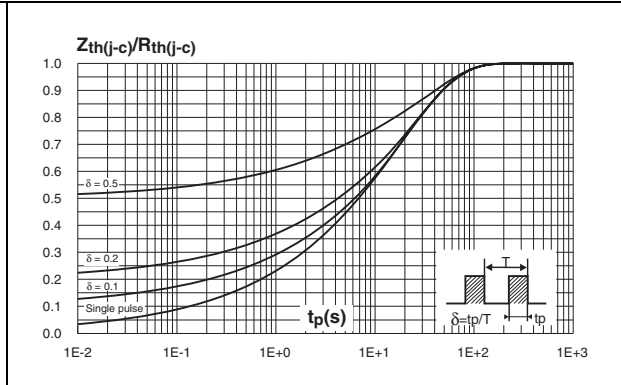


Figure 9. Reverse leakage current versus reverse voltage applied (typical values)

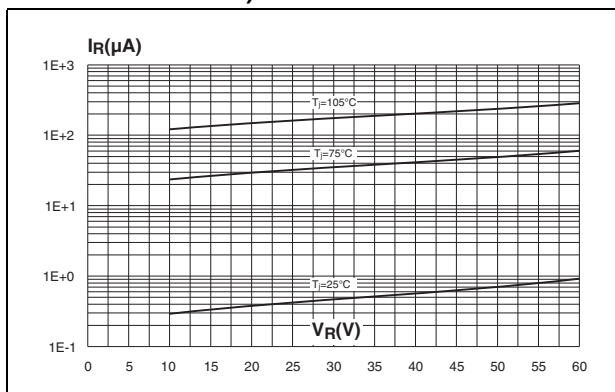


Figure 10. Junction capacitance versus reverse voltage applied (typical values)

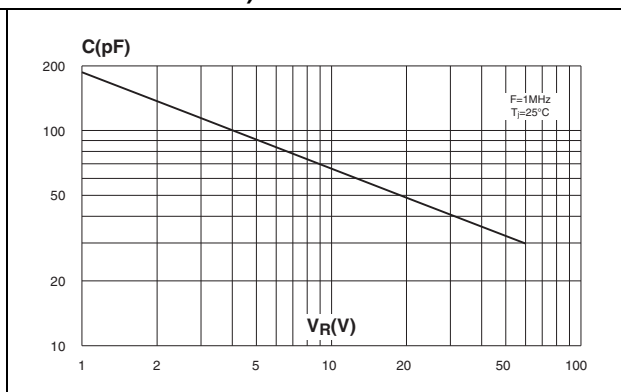


Figure 11. Forward voltage drop versus forward current (maximum values)

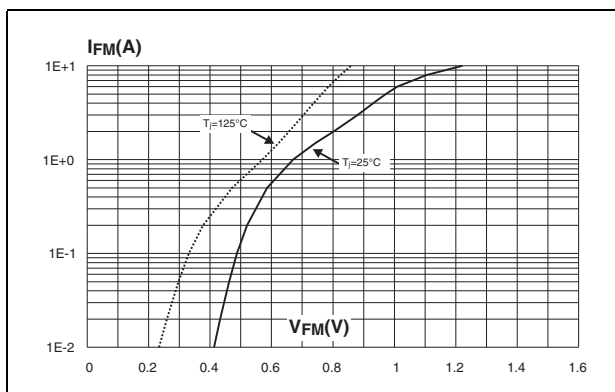


Figure 12. Thermal resistance junction to ambient versus copper surface under each lead (Epoxy printed circuit board FR4, copper thickness: $35 \mu\text{m}$) (SMA)

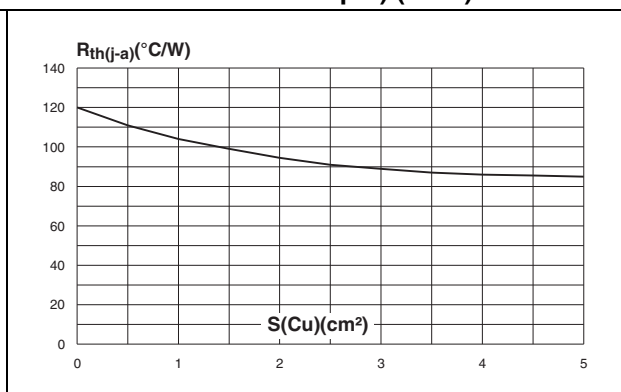
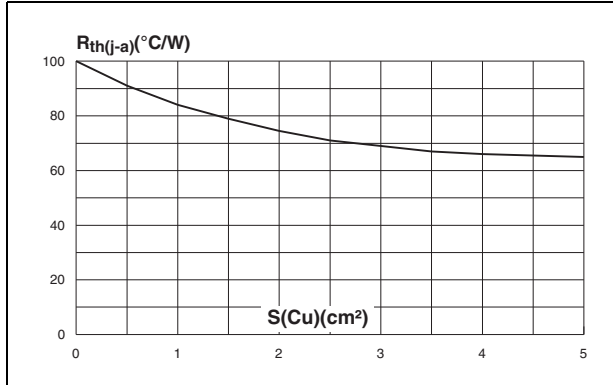


Figure 13. Thermal resistance junction to ambient versus copper surface under each lead (Epoxy printed circuit board FR4, copper thickness: 35 μm) (SMB)



2 Package information

- Epoxy meets UL94, V0
- Band indicates cathode

Figure 14. SMA package mechanical data

Ref	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A1	1.90	2.45	0.075	0.094
A2	0.05	0.20	0.002	0.008
b	1.25	1.65	0.049	0.065
c	0.15	0.40	0.006	0.016
D	2.25	2.90	0.089	0.114
E	4.80	5.35	0.189	0.211
E1	3.95	4.60	0.156	0.181
L	0.75	1.50	0.030	0.059

Figure 15. SMA footprint dimensions (in millimeters)

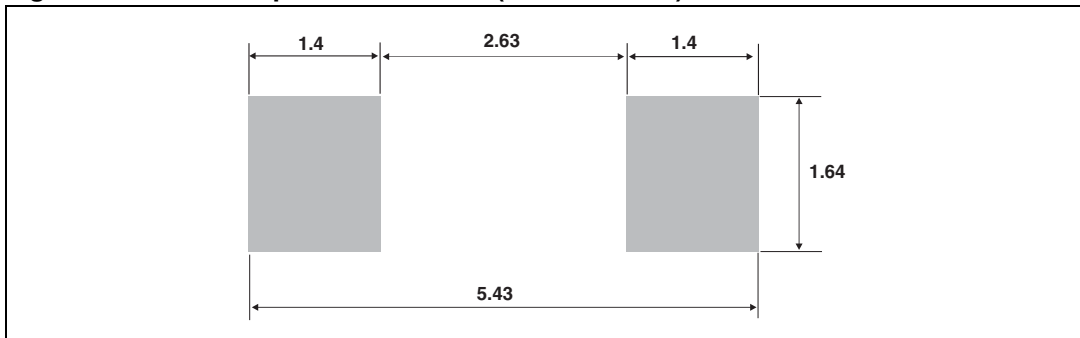
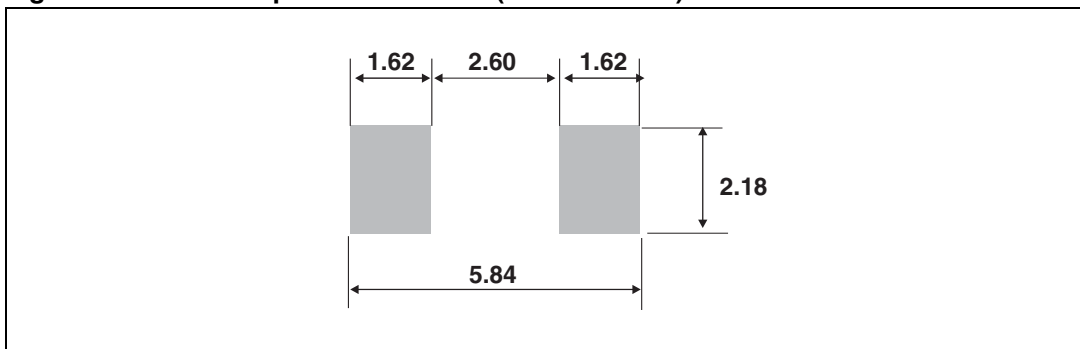


Figure 16. SMB package mechanical data

Ref	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A1	1.90	2.45	0.075	0.096
A2	0.05	0.20	0.002	0.008
b	1.95	2.20	0.077	0.087
c	0.15	0.40	0.006	0.016
E	5.10	5.60	0.201	0.220
E1	4.05	4.60	0.159	0.181
D	3.30	3.95	0.130	0.156
L	0.75	1.50	0.030	0.059

Figure 17. SMB footprint dimensions (in millimeters)



In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a lead-free second level interconnect. The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: www.st.com.

3 Ordering information

Ordering type	Marking	Package	Weight	Base qty	Delivery mode
STPS160A	GA6	SMA	0.068 g	5000	Tape and reel
STPS160U	E16	SMB	0.107 g	2500	Tape and reel

4 Revision history

Date	Revision	Description of changes
Jul-2003	6A	Last update.
Aug-2004	7	SMA package dimensions update. Reference A1 max changed from 2.70 mm (0.106 inc.) to 2.03 mm (0.080 inc).
16-Feb-2007	8	Reformatted to current standards. $I_{F(RMS)}$ removed from Table 1. Package dimensions and footprints updated. Ecopack statement added.

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